

ABSTRACT

WAFER PROCESSING METHOD

A wafer processing method for dividing a wafer into individual device chips along division lines is disclosed. The wafer processing method includes a back grinding step of grinding the back side of the wafer in the condition where a protective tape is attached to the front side of the wafer, thereby reducing the thickness of the wafer to a predetermined thickness, and a reinforcing insulation seal mounting step of mounting a reinforcing insulation seal capable of transmitting infrared light on the back side of the wafer. The wafer processing method further includes a modified layer forming step of applying a laser beam along each division line to thereby form a modified layer inside the wafer along each division line and a wafer dividing step of applying an external force to the wafer to thereby divide the wafer into the individual device chips along each division line.

(Figure 12B)